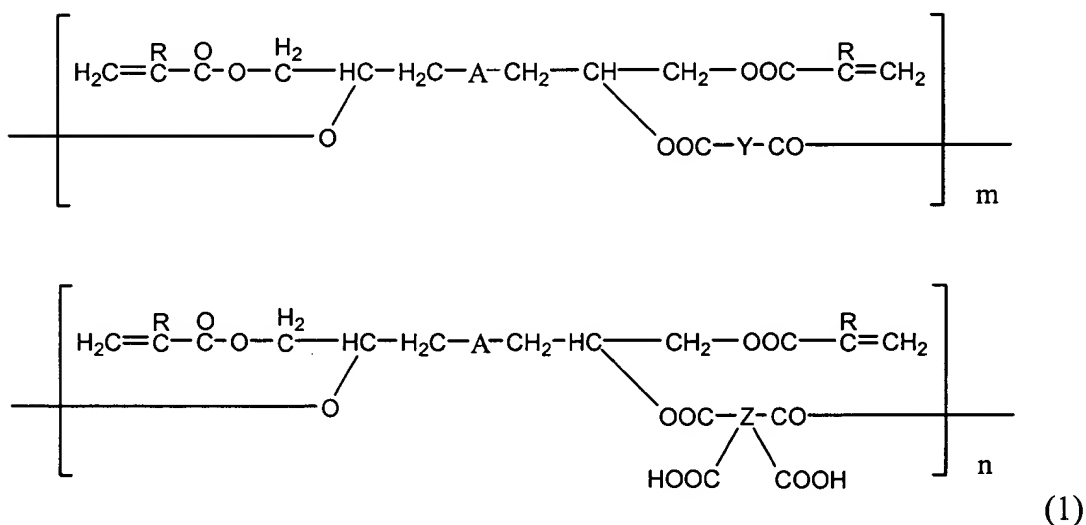


LISTING OF CLAIMS

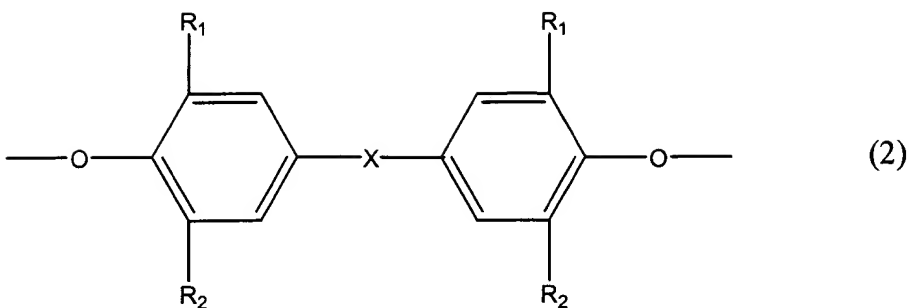
1. (currently amended) A photo- or heat-curable resin composition for forming a resin insulation layer in a printed wiring board comprising a resin-forming component and 0.1 to 1 parts by weight of ~~an inorganic filler~~ silica sol with ~~its~~ an average particle diameter in the range of 5 nm-0.5  $\mu$ m per 100 parts by weight of the resin-forming component

wherein the resin-forming component comprises:

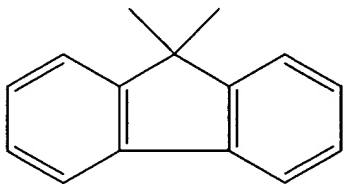
(A) 100 parts by weight of a photopolymerizable unsaturated compound represented by the following general formula (1)



wherein R is a hydrogen atom or a methyl group, A is a group represented by the formula (2)



(wherein  $R_1$  and  $R_2$  are independently hydrogen, an alkyl group with 1-5 carbon atoms, or a halogen),  $X$  is  $-CO-$ ,  $-SO_2-$ ,  $-C(CF_3)_2-$ ,  $-Si(CH_3)_2-$ ,  $-CH_2-$ ,  $-O-$ ,  $-S-$ ,



or a direct bond,  $Y$  and  $Z$  are respectively the residue of a polycarboxylic acid or its acid anhydride, and  $m$  and  $n$  are the number of repeating units at a molar ratio  $m/n$  0/100 - 100/0,

(B) 0-50 parts by weight of a compound containing an epoxy group,

(C) 0-10 parts by weight of a photopolymerization initiator or sensitizer,

~~wherein the inorganic filler is silica sol with its average particle diameter in the range of 5 nm-0.5  $\mu m$  per 100 parts by weight based on the combined weight of resin forming components~~

~~which consists of at least one selected from a photo or heat-polymerizable unsaturated compound and a condensable compound and the compound containing an epoxy group (B) and a curing agent of the compound (B).~~

2. (Canceled)

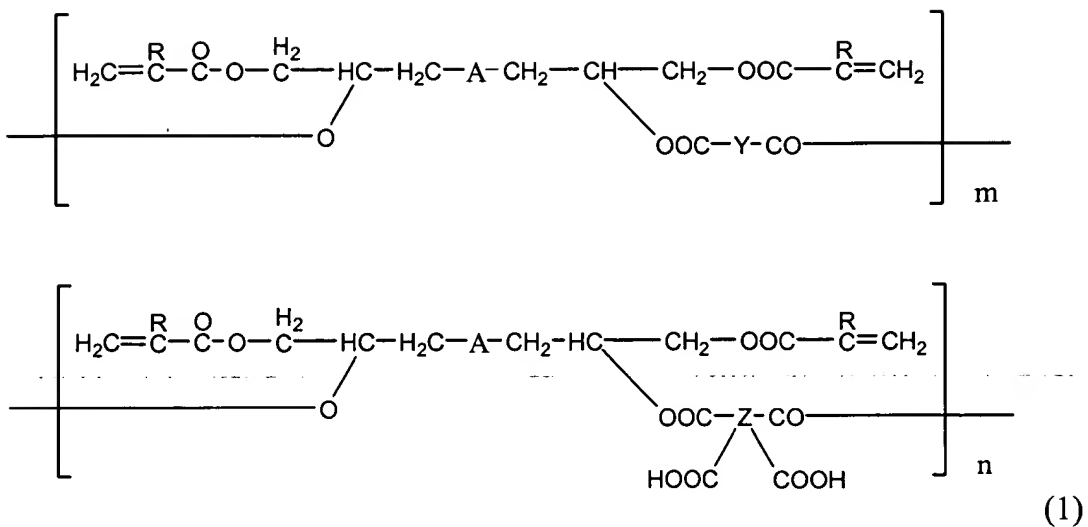
3. (Canceled)

4. (Cancelled)

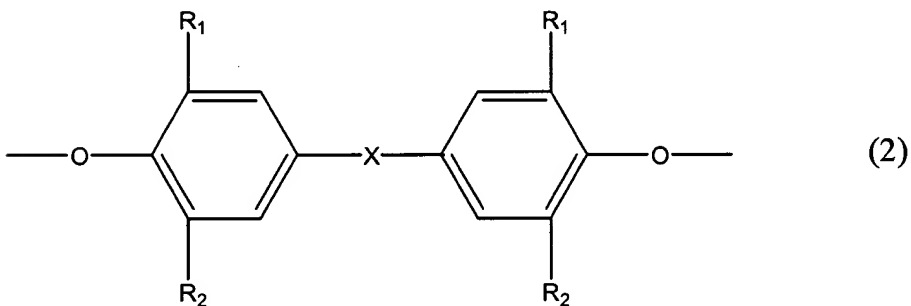
5. (Original) A multilayer printed wiring board wherein a resin insulation layer is formed by the cured product of a photo- or heat-curable resin composition as described in claim 1.

6. (New) A photo- or heat-curable resin composition comprising:

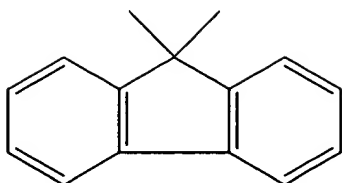
(A) 30 to 80 parts by weight of a photopolymerizable unsaturated compound; compound of formula (1)



wherein R is a hydrogen atom or a methyl group, A is a group represented by the formula (2)



(wherein R<sub>1</sub> and R<sub>2</sub> are independently hydrogen, an alkyl group with 1-5 carbon atoms, or a halogen), X is -CO-, -SO<sub>2</sub>-, -C(CF<sub>3</sub>)<sub>2</sub>-, -Si(CH<sub>3</sub>)<sub>2</sub>-, -CH<sub>2</sub>-, -O-, -S-,



or a direct bond, Y and Z are respectively the residue of a polycarboxylic acid or its acid anhydride, and m and n are the number of repeating units at a molar ratio m/n 0/100 - 100/0;

(B) 10 to 50 parts by weight of a compound containing an epoxy group;

(C) 10 to 40 parts by weight of a polyfunctional acrylate; and

(D) 0.1 to 1 part by weight of silica sol having an average particle diameter in the range of 10 to 100 nm.